



Printed Circuit Boards  
Interconnection Carriers

State of the Art: PCB's

Revisio

Datum:

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# PRINTED CIRCUIT BOARDS

01

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## Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 110 FR4 70 L50.35 P10

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

04\_110\_FR4\_70\_L50.35\_p10

Layers	in $\mu$	Material	Build-Up	Assembly
Layer-1	70 $\mu$	Copper		B
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
Layer-2	35 $\mu$	Copper		
	500 $\mu$	L-FR4		
Layer-3	35 $\mu$	Copper		
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
Layer-99	70 $\mu$	Copper		

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